



Solution brief

SECORA™ ID

Infineon's Java Card™ Solution Platform for ID Applications

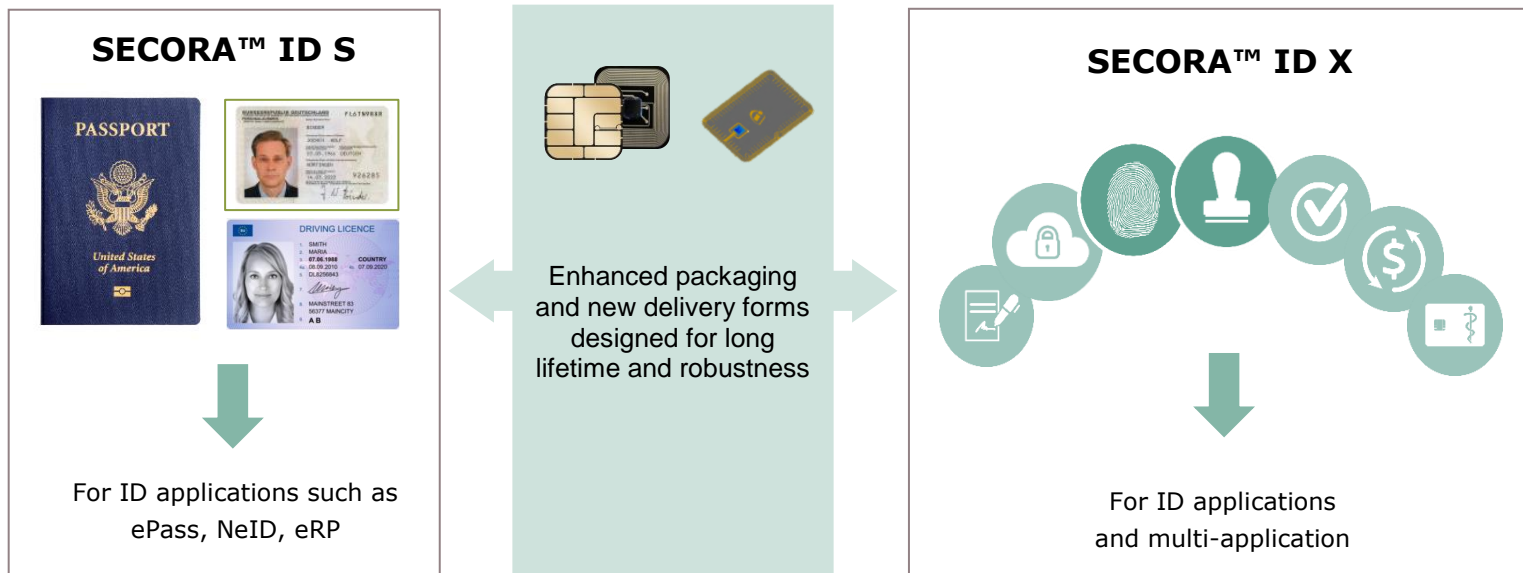
SECORA™ ID is a Java Card™ solution, which represents Infineon's engagement of offering a flexible development Java platform and efficient solutions for ID applications. Its portfolio comprises the ID S and ID X variants.

SECORA™ ID S is a Java open platform for eID application. which could also include a ready-to-use, optimized solution for standard government document applications. SECORA™ ID X is a high-end open platform to support standard/individual eID requirements and/or multi-application.

SECORA™ ID offers comprehensive applets choices including Infineon Applet Collection and ePasslet Suite by cryptovision GmbH. It enables customer's own applet development on top to implement their individual needs. Completed by Infineon and partner's ready-to-use software solutions, SECORA™ ID is an enablement platform offering customers a perfect solution combining typical ID application with special requirements together.

SECORA™ ID offers not only conventional smart card packages but also innovative and alternative packaging like Coil on Module.

Benefits	Feature	Advantage
Ready-to-use but also flexible	Dynamic Java Card 3.0.5 and optimized API for electronic document use cases	Efficient OS with flexible real open platform for serving diverse global and domestic electronic document
	Global Platform® 2.3.1	
One-stop-shop with ready-to-use solutions	Off-the-shelf CC certified chip + CC certified Java Card™ OS(targeted) - CC certified applets for eID(targeted)	Faster project work and time-to-market
	One supplier for chip, software and extensive package offering including inductive coupling technology Coil on Module Module (inductive coupling technology) with complementary antenna offering	Reduced supplier complexity
	Enhanced packaging and new delivery forms	Novel form factors
	Faster personalization performance combined with flashing services for customer applets based on Infineon's SOLID FLASH™	Reduced production costs Optimization of stock management
Highest possible customization	Applet development tools based on Eclipse for applet development	Full customization
Best-in-class cardholder experience	Fast contactless transaction speed and compliant with latest contactless performance requirements	Contactless robustness and performance
Rapid project migration	One-stop-shop with ready-to-use solutions and best-in-class support and documentation	Fast time-to-market Reduction of total-cost-of-ownership



Product Variants	SECORA™ ID S	SECORA™ ID X
Key differences	Ready-to-use and flexible	High performance supporting individual requirements and multi-application
Product description	Offering a Java open platform. Also available with a ready-to-use solution for standard government document applications. Ready to go solutions: Infineon Applet Collection	Flexible and high-end Java open platform supporting standard/individual requirements and/or multi-application for addressing project specific needs on eID application. Ready to go solutions: ePasslet Suite by cryptovision GmbH
Typical applications	Possible for several of below applications at once: <ul style="list-style-type: none"> ePassport National eID eDriving License eSignature eHIC (electronic health insurance card) ISO7816-4 Data Structure for Customization FIDO™ Authentication 	Possible for all of below applications at once: <ul style="list-style-type: none"> ePassport National eID eDriving License eSignature eVR (electronic vehicle registration) eHIC (electronic health insurance card) ISO7816-4 Data Structure for Customization Multi-application FIDO™ Authentication

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